

*拆分部位名称 Disassembly Unit/component description	*均质材料名称 Homogeneous Material Name. (e.g. Aluminum alloy)	物质名称 Substance Name (e.g. Copper (Cu))	*CAS No.	*物质重量 Substance Mass. (mg)	Content Rate(%) (均 质材料中的含 量 per homogeneous materials)
Solder Bump	Copper and Its Alloys	Copper	7440-50-8	0.00959	0.59999
	Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.526429	95.499998
	Precious Metals	Silver	7440-22-4	0.062336	3.90001
Semiconductor Device	Ceramics / Glass	Doped Silicon	7440-21-3	3.839367	100